Faculty of Electrical and Computer Engineering

The Institute of Electronic Packaging Technology offers a position as

Research Associate
(Subject to personal qualification employees are remunerated according to salary group E 13 TV-L)

starting as soon as possible. The position is limited until December 31th 2018 with the possibility of extension. The period of employment is governed by the Fixed Term Research Contracts Act (Wissenschaftszeitvertragsgesetz - WissZeitVG). The position offers the chance to obtain further academic qualification.

Tasks: The project focuses on the development of new electronics packages for 5G integrated circuit applications for the field of automotive electronics. Main goals of the development activities are miniaturization, high frequency ability and reliability of electronic systems considering chip package interactions. One of the project tasks is to research finite element based analysis of chip, package and system stress under thermo-mechanical loads. Established as well as new methodologies to analyse stresses in complex electronic systems have to be applied to solve the named tasks. This includes the determination of material data required. Coordination, preparation and execution of work packages related to finite element calculations as well as their verification against results from reliability tests and micro analysis have to be conducted.

Requirements: Candidates should have a university degree in Electrical Engineering, Mechanical Engineering, Materials Science or a comparable academic degree with grade Good at least; good knowledge and abilities in the fields of electronics packaging and reliability of electronics systems; good German and English language skills, high motivation, creativity, and ability to work in a team. Expertise and practical experience in the fields of numerical analysis using finite element approach, characterisation of packaging materials, and destructive and non-destructive micro analytics are favourably but no prerequisite.

Applications from women are particularly welcome. The same applies to people with disabilities. Please send your application documents until 28.06.2018 (stamped arrival date of the university central mail service applies) to: TU Dresden, Fakultät Elektrotechnik und Informationstechnik, Institut für Aufbau- und Verbindungstechnik der Elektronik, Herrn Dr.-Ing. Karsten Meier, Helmholtzstr. 10, 01069 Dresden. Please submit copies only, as your application will not be returned to you. Expenses incurred in attending interviews cannot be reimbursed.